

# **650V Super-Junction Power MOSFET**

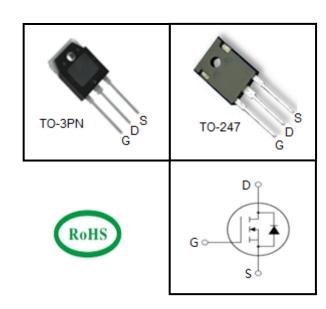
#### **FEATURES**

- $\bullet \quad \text{Very low FOM R}_{\text{DS(on)}} \times \text{Q}_{\text{g}} \\$
- 100% avalanche tested
- RoHS compliant

#### **APPLICATIONS**

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)

Device Marking and Package Information			
Device	Package	Marking	
TPV65R080C	TO-3PN	65R080C	
TPW65R080C	TO-247	65R080C	



<b>Absolute Maximum Ratings</b> $T_C = 25^{\circ}C$ , unless otherwise noted				
Parameter	Symbol	Value	Unit	
Drain-Source Voltage (V <sub>GS</sub> = 0V)	V <sub>DSS</sub>	650	V	
Continuous Drain Current	I <sub>D</sub>	47	Α	
Pulsed Drain Current (note1	I <sub>DM</sub>	141	Α	
Gate-Source Voltage	V <sub>GSS</sub>	±30	V	
Single Pulse Avalanche Energy (note2)	E <sub>AS</sub>	1120	mJ	
Avalanche Current (note1	I <sub>AR</sub>	8.7	Α	
Repetitive Avalanche Energy (note1)	E <sub>AR</sub>	1.76	mJ	
Power Dissipation (T <sub>C</sub> = 25°C)	P <sub>D</sub>	390	W	
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55~+150	°C	

Thermal Resistance				
Parameter	Symbol	Value	Unit	
Thermal Resistance, Junction-to-Case	R <sub>thJC</sub>	0.32	12.001	
Thermal Resistance, Junction-to-Ambient	R <sub>thJA</sub>	62	K/W	

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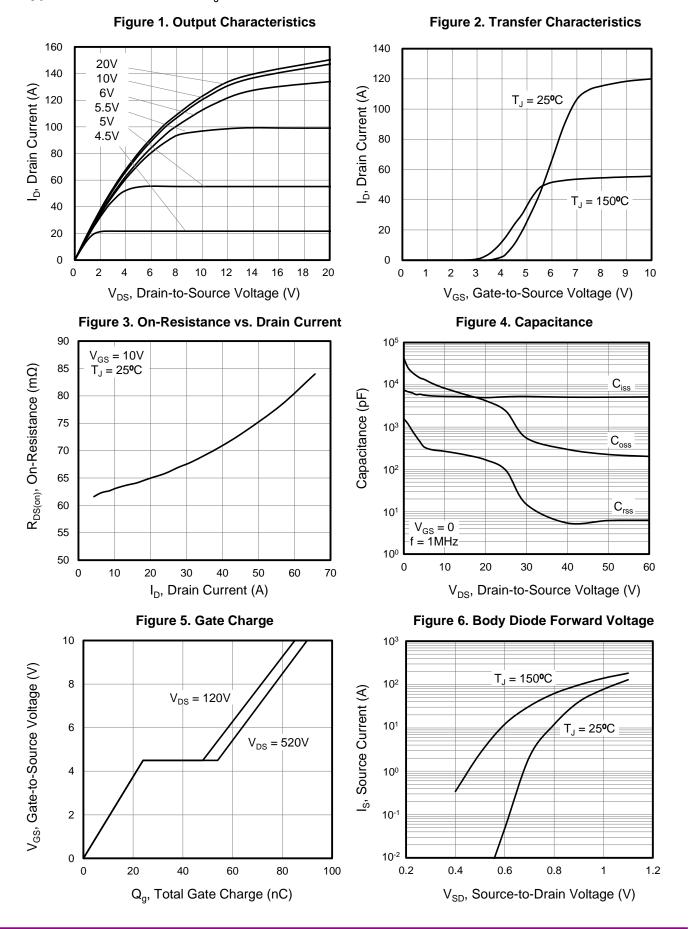
<b>Specifications</b> $T_J = 25^{\circ}C$ , unless otherwise noted						
Parameter	Symbol	Symbol Test Conditions	Value			Unit
	•	Min.	Тур.	Max.		
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_{D} = 250\mu A$	650			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 650V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			1	μA
Zero Gate Voltage Drain Gurrent		$V_{DS} = 650V, V_{GS} = 0V, T_{J} = 150^{\circ}C$			100	
Gate-Source Leakage	$I_{\rm GSS}$	$V_{GS} = \pm 30V$			±100	nA
Gate-Source Threshold Voltage	$V_{\rm GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.5		4.0	V
Drain-Source On-Resistance (Note3)	$R_{DS(on)}$	$V_{GS} = 10V, I_{D} = 20A$		65	80	mΩ
Forward Transconductance (Note3)	$g_{fs}$	$V_{DS} = 10V, I_{D} = 20A$		40		S
Dynamic				-		
Input Capacitance	C <sub>iss</sub>	\/ _ 0\/		5098		
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0V,$ $V_{DS} = 50V,$		225		pF
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1.0MHz		6.2		
Total Gate Charge	$Q_g$			90		
Gate-Source Charge	$Q_{gs}$	$V_{DD} = 520V, I_{D} = 47A,$ $V_{GS} = 10V$		24		nC
Gate-Drain Charge	$Q_{gd}$	93		30		
Turn-on Delay Time	t <sub>d(on)</sub>			16		
Turn-on Rise Time	t <sub>r</sub>	$V_{DD} = 400V, I_{D} = 26A,$		12		
Turn-off Delay Time	t <sub>d(off)</sub>	$R_G = 1.7\Omega$		83		ns
Turn-off Fall Time	t <sub>f</sub>			5		
Drain-Source Body Diode Characteristics						
Continuous Body Diode Current	I <sub>s</sub>	T 0500			47	٨
Pulsed Diode Forward Current	I <sub>SM</sub>	$T_C = 25^{\circ}C$			141	А
Body Diode Voltage	V <sub>SD</sub>	$T_J = 25^{\circ}C$ , $I_{SD} = 47A$ , $V_{GS} = 0V$		0.9	1.2	V
Reverse Recovery Time	t <sub>rr</sub>			720		ns
Reverse Recovery Charge	Q <sub>rr</sub>	$V_R = 400V, I_F = 26A,$ $di_F/dt = 100A/\mu s$		19		μC
Peak Reverse Recovery Current	I <sub>rrm</sub>			52		А

#### **Notes**

- 1. Repetitive Rating: Pulse Width limited by maximum junction temperature
- 2.  $I_{AS}$  = 15A,  $V_{DD}$  = 50V,  $R_{G}$  = 25 $\Omega$ , Starting  $T_{J}$  = 25 $^{\circ}$ C
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 1%



### **Typical Characteristics** $T_J = 25^{\circ}\text{C}$ , unless otherwise noted



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Figure 7. On-Resistance vs. Temperature

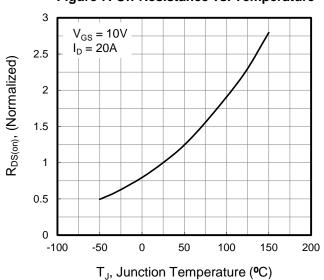


Figure 8. Threshold Voltage vs. Temperature

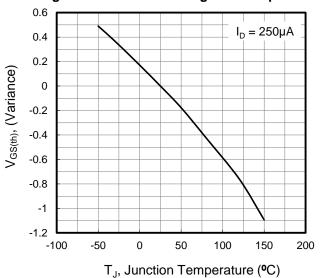
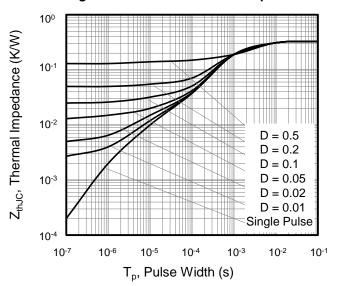


Figure 9. Transient Thermal Impedance



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Figure A: Gate Charge Test Circuit and Waveform

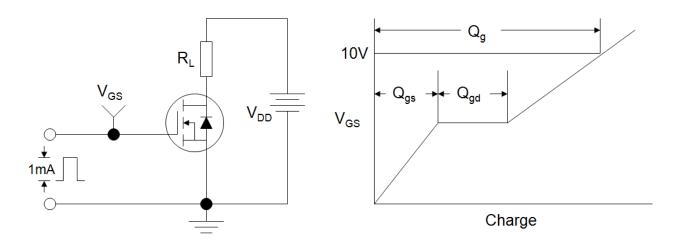


Figure B: Resistive Switching Test Circuit and Waveform

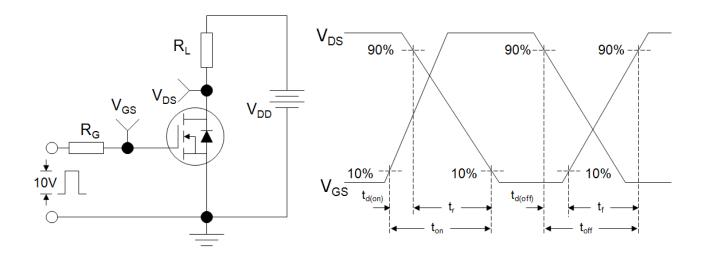
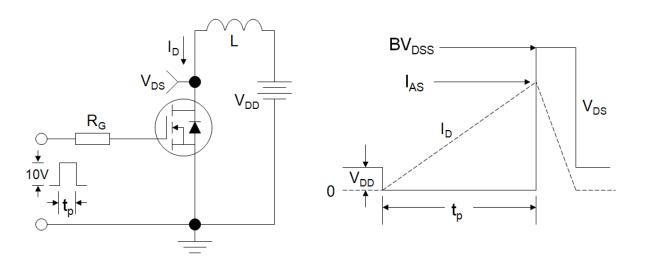


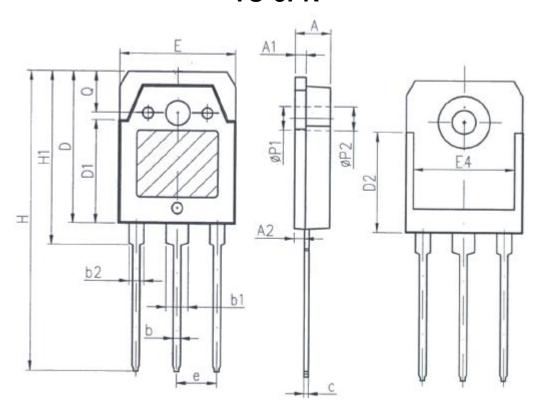
Figure C: Unclamped Inductive Switching Test Circuit and Waveform



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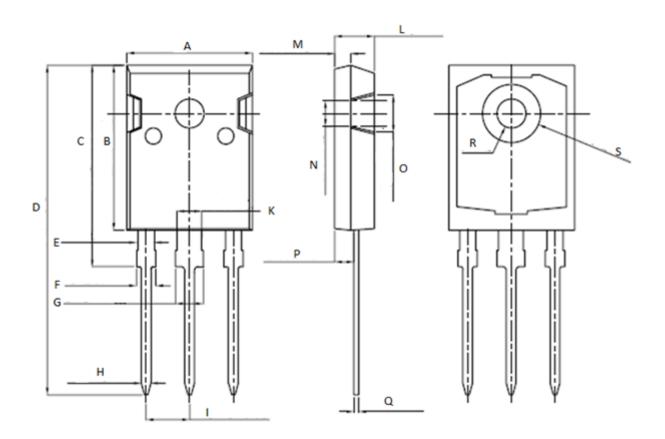






Unit:mm			
Symbol	Min.	Max.	
Α	4. 6	5	
A1	1. 4	1. 65	
A2	1. 18	1. 58	
b	0.8	1. 2	
b1	2. 8	3. 2	
b2	1.8	2. 2	
С	0. 5	0. 75	
D	19. 6	20. 2	
D1	13. 55	14. 25	
D2	12. 9REF		
E	15. 35	15. 85	
E4	12. 6	-	
е	5. 45TYP		
Н	40. 1	40. 9	
H1	23. 15	23. 65	
P1	3. 2REF		
P2	3. 5REF		

## **TO-247**



Unit: mm				
Symbol	Min.	Max.		
Α	15. 95	16. 25		
В	20. 85	21. 25		
С	20. 95	21. 35		
D	40. 5	40. 9		
E	1. 9	2. 1		
F	2. 1	2. 25		
G	3. 1	3. 25		
Н	1.1	1. 3		
I	5. 40	5. 50		

Unit: mm			
Symbol	Min.	Max.	
K	2. 90	3. 10	
L	4. 90	5. 30	
M	1. 90	2. 10	
N	4. 50	4. 70	
0	5. 40	5. 60	
Р	2. 29	2. 49	
Q	0. 51	0. 71	
R	ф 3. 5	ф 3. 7	
S	ф 7. 1	ф 7. 3	



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